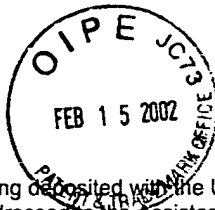


Docket No.: GR 98 P 1075 P



2621, 2721
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By: [Signature]

Date: January 25, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Manfred Fries et al.
Applic. No. : 09/627,181
Filed : July 27, 2000
Title : Chip Smart Card Module for Biometric Sensors
Art Unit : 2721

#5
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FEB 22 2002
Technology Center 2100
6/27/02

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

International Publication WO 96/42109 (Bitschnau et al.), dated December 27, 1996;


Russian Examination Report dated November 10, 2001.

In accordance with 37 C.F.R. 1.97(e) the undersigned herewith states that each item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications,

patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,



For Applicants

Mark P. Weichselbaum
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Date: January 25, 2002

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